



Product Summary

$V_{(BR)DSS}$	$R_{DS(on)TYP}$	I_D
-30V	14m Ω @-10V	-30A
	19m Ω @-4.5V	

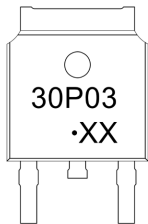
Feature

- Trench Technology Power MOSFET
- Low $R_{DS(ON)}$
- Low Gate Charge
- Low Gate Resistance
- 100% UIS Tested

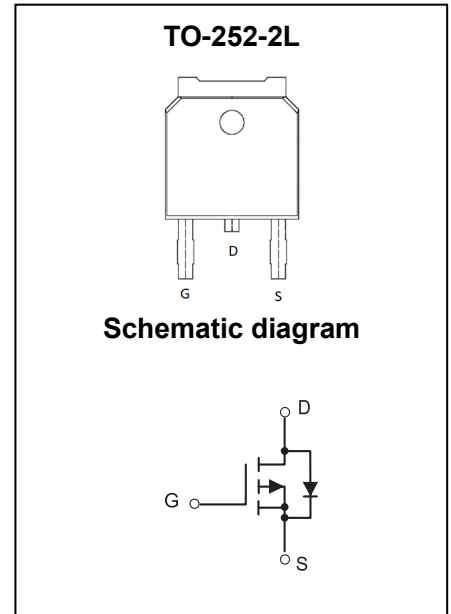
Application

- Power Switching Application

MARKING:



30P03 = Device Code
XX = Date Code
Solid Dot = Green Indicator



ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain - Source Voltage	V_{DS}	-30	V
Gate - Source Voltage	V_{GS}	± 20	V
Continuous Drain Current ¹	I_D	-30	A
Continuous Drain Current ¹	I_D	-22	A
	$T_C = 25^\circ\text{C}$		
	$T_C = 100^\circ\text{C}$		
Pulsed Drain Current ²	I_{DM}	-120	A
Single Pulsed Avalanche Current ³	I_{AS}	24	A
Single Pulsed Avalanche Energy ³	E_{AS}	144	mJ
Power Dissipation ⁵	P_D	50	W
	$T_C = 25^\circ\text{C}$		
Thermal Resistance from Junction to Ambient ⁶	$R_{\theta JA}$	50	$^\circ\text{C}/\text{W}$
Thermal Resistance from Junction to Case	$R_{\theta JC}$	2.5	$^\circ\text{C}/\text{W}$
Junction Temperature	T_J	150	$^\circ\text{C}$
Storage Temperature	T_{STG}	-55~ +150	$^\circ\text{C}$

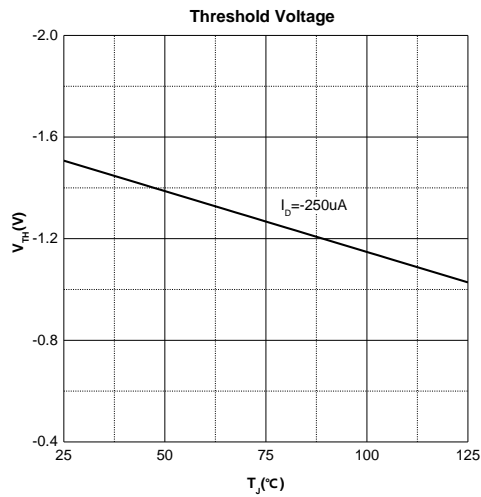
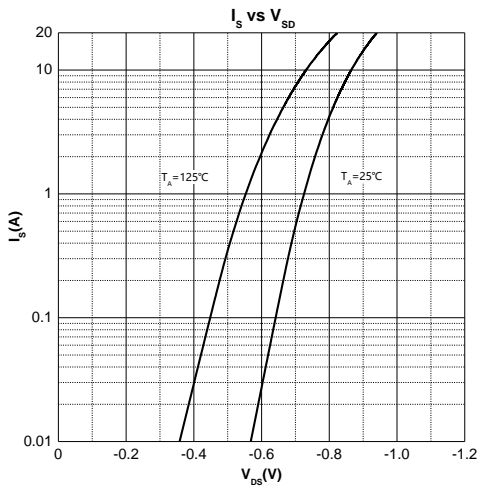
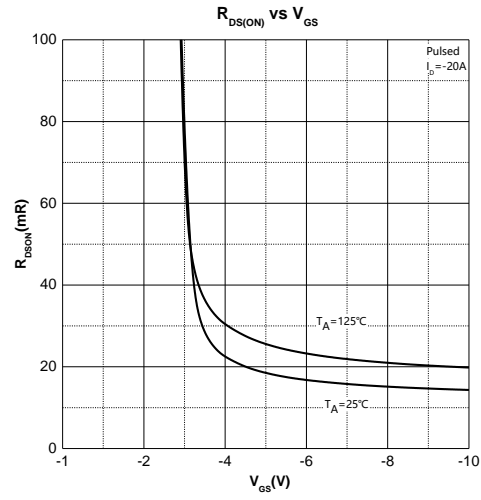
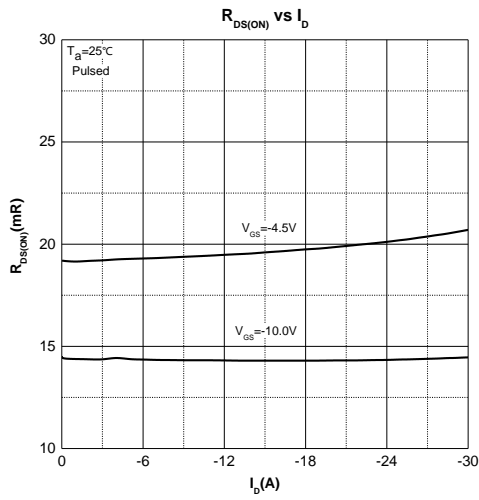
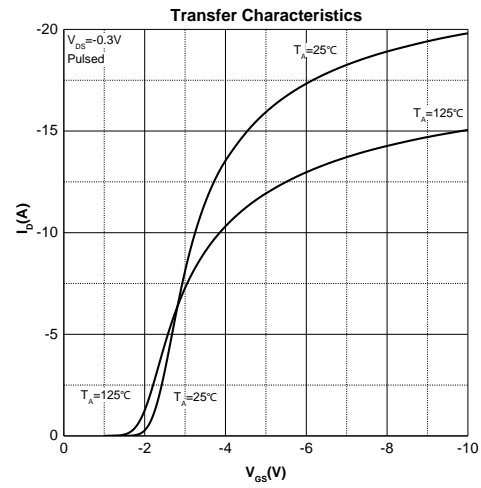
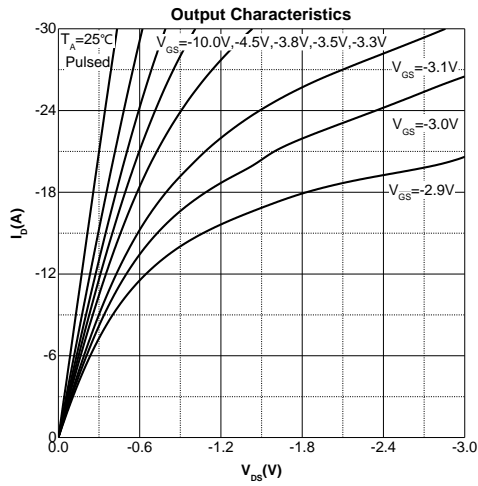
MOSFET ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$ unless otherwise noted)

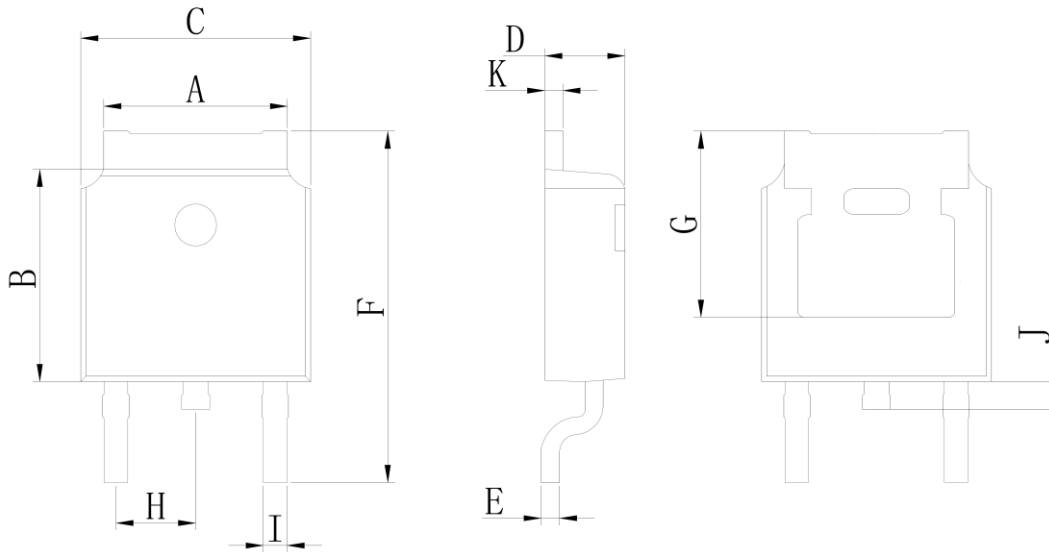
Parameter	Symbol	Test Condition	Min	Type	Max	Unit
Off Characteristics						
Drain - Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = -250\mu A$	-30			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = -30V, V_{GS} = 0V$			-1	μA
Gate - Body Leakage Current	I_{GSS}	$V_{GS} = \pm 20V, V_{DS} = 0V$			± 100	nA
On Characteristics⁴						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = -250\mu A$	-1	-1.5	-2.5	V
Drain-source On-resistance	$R_{DS(on)}$	$V_{GS} = -10V, I_D = -20A$		14	18	m Ω
		$V_{GS} = -4.5V, I_D = -15A$		19	30	
Dynamic Characteristics						
Input Capacitance	C_{iss}	$V_{DS} = -15V, V_{GS} = 0V, f = 1MHz$		1961		pF
Output Capacitance	C_{oss}			214		
Reverse Transfer Capacitance	C_{rss}			196		
Gate Resistance	R_g	$V_{DS} = 0V, V_{GS} = 0V, f = 1MHz$		8		Ω
Switching Characteristics						
Total Gate Charge	Q_g	$V_{DS} = -15V, V_{GS} = -10V, I_D = -20A$		40.6		nC
Gate-source Charge	Q_{gs}			4.9		
Gate-drain Charge	Q_{gd}			7.4		
Turn-on Delay Time	$t_{d(on)}$	$V_{DD} = -15V, V_{GS} = -10V,$ $R_L = 0.75\Omega, R_G = 3\Omega$		10		ns
Turn-on Rise Time	t_r			11.5		
Turn-off Delay Time	$t_{d(off)}$			55		
Turn-off Fall Time	t_f			22		
Source - Drain Diode Characteristics						
Diode Forward Voltage ⁴	V_{SD}	$V_{GS} = 0V, I_S = -15A$			-1.2	V

Notes :

- 1.The maximum current rating is limited by package.And device mounted on a large heatsink
- 2.Pulse Test : Pulse Width $\leq 10\mu s$, duty cycle $\leq 1\%$.
- 3.EAS condition: $V_{DD} = -15V, V_{GS} = -10V, L = 0.5mH, R_G = 25\Omega$ Starting $T_J = 25^\circ\text{C}$.
- 4.Pulse Test : Pulse Width $\leq 300\mu s$, duty cycle $\leq 2\%$.
- 5.The power dissipation P_D is limited by $T_{J(MAX)} = 150^\circ\text{C}$.And device mounted on a large heatsink
- 6.Device mounted on $1in^2$ FR-4 board with 2oz. Copper, in a still air environment with $T_A = 25^\circ\text{C}$.

Typical Characteristics



TO-252-2L Package Information


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	5.050	5.650	0.199	0.222
B	5.800	6.400	0.228	0.252
C	6.250	6.850	0.246	0.270
D	2.200	2.400	0.087	0.094
E	0.400	0.600	0.016	0.024
F	9.710	10.310	0.382	0.406
G	5.050	5.650	0.199	0.222
H	2.100	2.500	0.083	0.098
I	0.700	0.900	0.028	0.035
J	0.500	0.900	0.020	0.035
K	0.400	0.600	0.016	0.024